

Please Direct All Correspondence to Customer Number **20995****AMENDMENT / RESPONSE TRANSMITTAL**

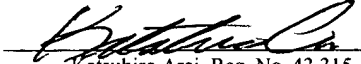
Applicant : Takeshi MATSUMURA, et al.  
 App. No : 10/678,855  
 Filed : October 3, 2003  
 For : DICING/DIE-BONDING FILM,  
 METHOD OF FIXING CHIPPED  
 WORK AND SEMICONDUCTOR  
 DEVICE  
 Examiner : Laura M. Schillinger  
 Art Unit : 2813

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

October 12, 2005

(Date)

  
 Katsuhiro Arai, Reg. No. 43,315
**Mail Stop AF**

Commissioner for Patents  
 P.O. Box 1450  
 Alexandria, VA 22313-1450

Sir:

Transmitted herewith for filing in the above-identified application are the following enclosures:

(X) Amendment After Final in nineteen (19) pages.

The fee has been calculated as shown below:

FEE CALCULATION				
FEE TYPE		FEE CODE	CALCULATION	TOTAL
Excess Claims > 20	6 - 20 = 0	1202 (\$50)	0 x 50 =	\$0
Independent > 3	1 - 3 = 0	1201 (\$200)	0 x 200 =	\$0
1 Month Extension	1.17(a)(1)	1251 (\$120)		\$120
			<b>TOTAL FEE DUE</b>	<b>\$120</b>

(X) An extension of time is hereby requested by payment of the appropriate fee indicated above.

(X) A check in the amount of \$120.00 is enclosed.

(X) Return prepaid postcard.

Docket No.: UNIU79.014AUS

October 12, 2005

App. No.: 10/678,855

Page 2 of 2

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- (X) Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.



Katsuhiro Arai

Registration No. 43,315

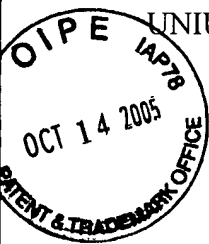
Attorney of Record

Customer No. 20,995

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UNIU79.014AUS

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

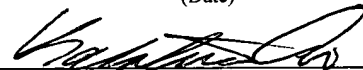
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AMENDMENT AFTER FINAL

**Mail Stop AF**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed June 14, 2005, please reconsider the present application in light of the following amendments and comments.

**Summary of Interview** begins on page 2 of this paper.

**Amendments to the Specification** begin on page 3 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 15 of this paper.

**Remarks/Arguments** begin on page 17 of this paper.

### **SUMMARY OF INTERVIEW**

Applicant wishes to thank Examiner Schillinger for the courteous telephone interview extended to Applicant's representative that was initiated by Applicant and conducted on September 15, 2005.

#### **Exhibits or demonstrations shown**

A sheet comparing Claim 1 and Fig. 1 was submitted by fax for the telephone interview.

#### **Identification of Prior Art Discussed**

Senoo (US 5,705,016) was discussed.

#### **Proposed Amendments**

None.

#### **Principal Arguments and Other Matters**

The structures which Claim 1 is intended to mean were explained, and according to the understanding of Claim 1, Senoo does not teach the structures of Claim 1.

#### **Results of Interview**

The Examiner asserted that Claim 1 could not be understood as is intended and needs to be rewritten.